

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/23/14206	
1.3 Title of PCN	ASE Kaohsiung (Taiwan) additional source for STM32H74x/75x products in UFBGA 10x10 package	
1.4 Product Category	STM32H74x, STM32H75x	
1.5 Issue date	2023-10-19	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ASE Kaohsiung Taiwan

4. Description of change

	Old	New
4.1 Description	Back-end source: - Amkor ATP Philippines	Back-end sources: - Amkor ATP Philippines - ASE Kaohsiung Taiwan - Additional source For more information, please refer to PCN14206 – Additional information attached document.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact on product Form, Fit, Function Visual aspect (color) might change depending on substrate material. Package darkness might change depending on molding compound. Marking position and size could be different upon assembly site, without any loss of information.	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Change is visible through assembly traceability plant, in the marking: - "7B" for Amkor ATP Philippines - "AA" for ASE Kaohsiung Taiwan Please refer to PCN 14206 – Additional information attached document.
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7. Timing / schedule

7.1 Date of qualification results	2023-09-22
7.2 Intended start of delivery	2024-01-10
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	14206 MDG-MCD-RER2021 V2.0 - PCN12916 - PCN14206 - ASE KH(Taiwan) xFBGA package Bonding Wire - Reliab Rprt.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-10-19

9. Attachments (additional documentations)

14206 Public product.pdf
14206 MDG-MCD-RER2021 V2.0 - PCN12916 - PCN14206 - ASE KH(Taiwan) xFBGA package Bonding Wire - Reliab Rprt.pdf
14206 PCN14206 Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H750IBK6	
	STM32H750IBK6TR	

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